

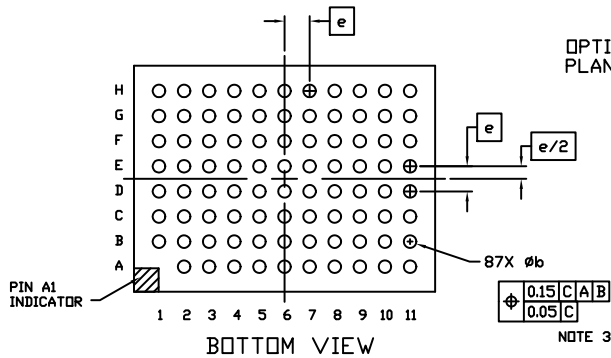
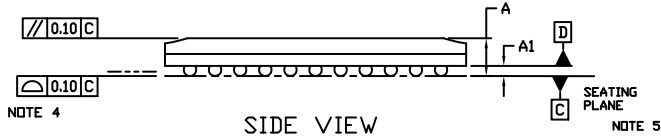
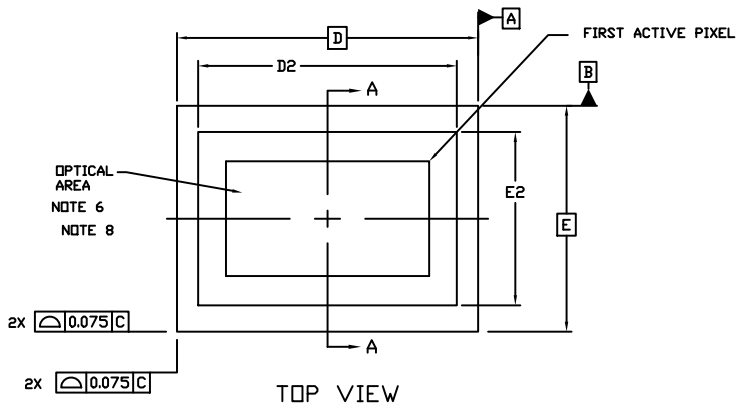
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



IBGA87 12x9  
CASE 503BR  
ISSUE A

DATE 22 JUN 2017

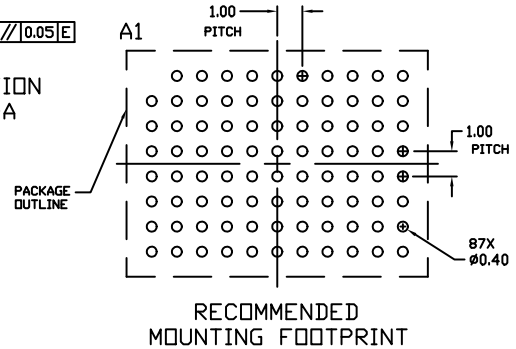
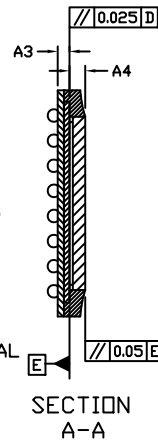


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. MAXIMUM ROTATION OF THE OPTICAL AREA RELATIVE TO D AND E WILL BE 0.5°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST PIXEL DEFINITIONS.
7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=-220.41 MICRONS, Y=-147.01 MICRONS ±75 MICRONS.

NOTE 7

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.65
A1	0.35	0.45
A3	0.425	0.525
A4	0.575	0.675
b	0.45	0.55
D	12.00	BSC
D2	10.20	10.40
E	9.00	BSC
E2	6.80	7.00
e	1.00	BSC



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